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TEXAS INSTRUMENTS

PMP30249 REV B Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	C1	1	270uF	EEHZA1V271P	Panasonic	CAP, Polymer Hybrid, 270 µF, 35 V, +/- 20%, 20 ohm, 10x10 SMD	10x10
2	C6, C14, C17, C22, C26, C32	6	0.1uF		MuRata	CAP, CERM, 0.1 μF, 50 V, +/- 10%, X7R, 0603	0603
3	C10, C11, C31	3	4.7uF		MuRata	CAP, CERM, 4.7 μF, 50 V, +/- 10%, X7R, 1210	1210
4	C15	1	0.47uF	GRM21BR72A474KA73L		CAP, CERM, 0.47 μF, 100 V, +/- 10%, X7R, 0805	0805
5	C16	1	4.7uF	GRM188R61C475KAAJ	MuRata	CAP, CERM, 4.7 µF, 16 V, +/- 10%, X5R, 0603	0603
6	C20, C21, C23, C24	4	47uF		MuRata	CAP, CERM, 47 μF, 10 V, +/- 10%, X7R, 1210	1210
7	C25	1	33pF	06035A330JAT2A	AVX	CAP, CERM, 33 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
8	C27	1	0.01uF	C1608X7R2A103M	TDK	CAP, CERM, 0.01 μF, 100 V, +/- 20%, X7R, 0603	0603
9	C28	1	100pF		MuRata	CAP, CERM, 100 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
10	C30	1	6800pF		MuRata	CAP, CERM, 6800 pF, 50 V, +/- 10%, X7R, 0603	0603
11	D2	1	60V		NXP Semiconductor	Diode, Schottky, 60 V, 1 A, SOD-323F	SOD-323F
12	D3	1	40V	MBR0540T1G	ON Semiconductor	Diode, Schottky, 40 V, 0.5 A, SOD-123	SOD-123
13	J1	1		1729018	Phoenix Contact	TERM BLOCK 2POS 5mm, TH	10x10x8.1 mm
14	J2, J5	2		61300211121	Wurth Elektronik	Header, 2.54 mm, 2x1, Gold, TH	Header, 2.54mm, 2x1, TH
15	J4, J6	2		61300311121	Wurth Elektronik	Header, 2.54 mm, 3x1, Gold, TH	Header, 2.54mm, 3x1, TH
16	L4	1	3.3uH	XAL1060-332MEB	Coilcraft	Inductor, Shielded, Composite, 3.3 µH, 16.8 A, 0.0072 ohm, AEC-Q200 Grade 1, SMD	Inductor, 10x6x11.3mm
17	Q1, Q3	2	40V	SQJA88EP	Vishay-Siliconix	MOSFET, N-CH, 40 V, 30 A, AEC-Q101, PowerPAK_SO-8L	PowerPAK_SO-8L
18	R4	1	10.0k	CRCW060310K0FKEA	Vishay-Dale	RES, 10.0 k, 1%, 0.1 W, 0603	0603
19	R6	1	2.21	CRCW06032R21FKEA	Vishay-Dale	RES, 2.21, 1%, 0.1 W, 0603	0603
20	R8, R9, R12, R14, R19	5	0	CRCW06030000Z0EA	Vishay-Dale	RES, 0, 5%, 0.1 W, 0603	0603
21	R10	1	0.007	WSL20107L000FEA18	Vishay-Dale	RES, 0.007, 1%, 1 W, 2010	2010
22	R15, R16	2	49.9	CRCW060349R9FKEA	Vishay-Dale	RES, 49.9, 1%, 0.1 W, 0603	0603
23	R17	1	4.42k	CRCW06034K42FKEA	Vishay-Dale	RES, 4.42 k, 1%, 0.1 W, 0603	0603
24	R18	1	34.8k	CRCW060334K8FKEA	Vishay-Dale	RES, 34.8 k, 1%, 0.1 W, 0603	0603
25	R20	1	20.0k	CRCW060320K0FKEA	Vishay-Dale	RES, 20.0 k, 1%, 0.1 W, 0603	0603
26	R22	1	54.9k	CRCW060354K9FKEA	Vishay-Dale	RES, 54.9 k, 1%, 0.1 W, 0603	0603
27	TP1, TP2	2	White	5002	Keystone	Test Point, Miniature, White, TH	White Miniature Testpoint
28	TP3, TP4	2	Triple	1598-2	Keystone	Terminal, Turret, TH, Triple	Keystone1598-2
29	TP6	1		5012	Keystone	Test Point, Multipurpose, White, TH	White Multipurpose Testpoint
30	U2	1		LM25141QRGEQ1	Texas Instruments	IC, PWM, Buck Controller, w/ Dither	RGE0024H

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